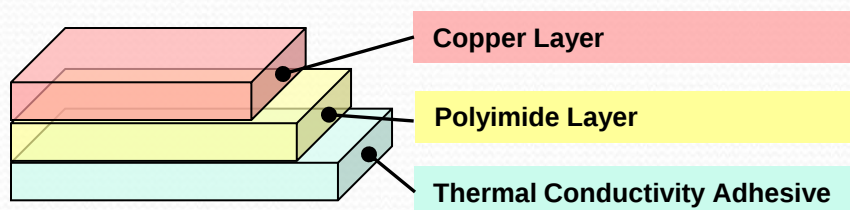


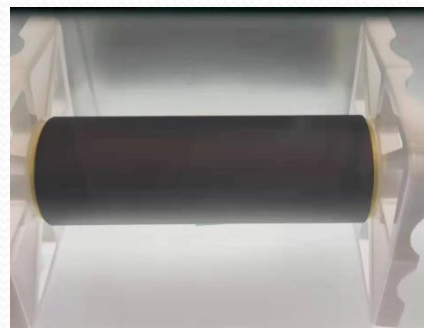
导热铜箔基板

Thermal Conductivity Copper Clad Laminate

◆ 产品叠构 Product Structure



◆ 产品实例 Product Samples



TCBSR3035

◆ 产品特点 Product Feature

- 超薄散热材料 Ultra-thin cooling material
- 高导热效率 High thermal conductivity
- 高耐击穿强度 High breakdown resistance
- 极佳之环境可靠度 Excellent environmental reliability

◆ 产品特性 Characteristics

检验项目 Test Items	实验条件 Condition of Testing	单位 Units	产品Product		测试方法 Test Method
			TCBSR3035	TCBSR3070	
厚度 (Thickness)	A	μm	65±10%	100±10%	APLUS SPEC
剥离强度 (Peel strength)	A	kgf/cm	≥ 1.0	≥ 1.0	IPC-TM-650 2.4.9
绝缘破坏电压 (Breakdown voltage)	AC	kV	> 2	> 2	ASTM B149-79a
导热率 (Thermal conductivity)	A	W/mk	> 0.8	> 0.8	ASTM B5470
介电常数 Dk (Dielectric constant)	@1M Hz	-	5.3	5.3	IPC-TM-650 2.5.5.13
介电损失 Df (Dissipation factor)	@1M Hz	-	0.018	0.018	
焊锡耐热性 (Solder resistance)	10 seconds at 300℃	-	PASS	PASS	IPC-TM-650 2.4.13
耐燃性 (Flame class)	A	-	V-0	V-0	UL 94
储存期限 (Shelf life)	≤5℃, 40-70%RH	month	3months in the original producing		APLUS SPEC

*所有数据为测试代表值 All data are representative value and not guarantee.